

Title (en)

INTEGRATED CIRCUIT AND METHOD FOR MAKING SAME

Title (de)

INTEGRIERTER SCHALTKREIS UND HERSTELLUNGSVERFAHREN

Title (fr)

CIRCUIT INTEGRE ET PROCEDE DE FABRICATION

Publication

**EP 1350267 A1 20031008 (FR)**

Application

**EP 02710090 A 20020109**

Priority

- FR 0200054 W 20020109
- FR 0100419 A 20010112

Abstract (en)

[origin: WO02056370A1] In one particular embodiment, the integrated circuit comprises a load storing semiconductor device comprising at least a control transistor T and a storage capacitor TRC. The device comprises a substrate including a lower region containing at least a buried capacitive trench TRC forming said storage capacitor, a casing CS located above said lower region of the substrate. The control transistor T is produced in and on the casing and said capacitive trench is located beneath the transistor and is in contact with the casing.

[origin: WO02056370A1] In one particular embodiment, the integrated circuit comprises a load storing semiconductor device comprising at least a control transistor T and a storage capacitor TRC. The device comprises a substrate including a lower region containing at least a buried capacitive trench TRC forming said storage capacitor, a casing CS located above said lower region of the substrate. The control transistor T is produced in and on the casing and said capacitive trench is located beneath the transistor and is in contact with the casing.

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**H01L 21/8242; H01L 27/108; H01L 27/146**

IPC 8 full level

**H01L 21/8242** (2006.01); **H01L 27/108** (2006.01)

CPC (source: EP US)

**H01L 27/14683** (2013.01 - EP US); **H01L 29/808** (2013.01 - EP US); **H10B 12/038** (2023.02 - EP US); **H10B 12/05** (2023.02 - EP US); **H10B 12/373** (2023.02 - EP US)

Citation (search report)

See references of WO 02056370A1

Designated contracting state (EPC)

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DOCDB simple family (publication)

**WO 02056370 A1 20020718; WO 02056370 A8 20020808**; EP 1350267 A1 20031008; FR 2819632 A1 20020719; FR 2819632 B1 20030926; US 2004113193 A1 20040617; US 2007015326 A1 20070118; US 7115933 B2 20061003; US 7470585 B2 20081230

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